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# TinyLogic UHS 1-of-2 Non-Inverting De-multiplexer with 3-STATE Deselected Output

# NC7SZ18

#### **Description**

The NC7SZ18 is a 1–of–2 non–inverting demultiplexer. The device will buffer the data on the A pin and pass to either output  $Y_0$  or  $Y_1$  dependent on whether state of the select pin (S) is LOW or HIGH respectively. The deselected output will be placed into a high impedance state. The device is fabricated with advanced CMOS technology to achieve ultra high speed with high output drive while maintaining low static power dissipation over a broad  $V_{\rm CC}$  operating range. The device is specified to operate over the 1.65 V to 5.5 V  $V_{\rm CC}$  operating range. The inputs and outputs are high impedance when  $V_{\rm CC}$  is 0 V. Inputs tolerate voltages up to 5.5 V independent of  $V_{\rm CC}$  operating range.

#### **Features**

- Ultra High-Speed:  $t_{PD} = 2.5$  ns Typical at 5 V  $V_{CC}$
- High Impedance Output when Deselected
- Broad V<sub>CC</sub> Operating Range: 1.65 V to 5.50 V
- Power Down High Impednce Inputs / Outputs
- Over-Voltage Tolerance Inputs Facilitate 5 V to 3 V Translation
- Proprietary Noise / EMI Reduction Circuitry
- Ultra-Small MicroPak<sup>TM</sup> Packages
- These Devices are Pb-Free, Halogen Free/BFR Free and are RoHS Compliant



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SIP6 1.45x1.0 CASE 127EB





UDFN6 1.0X1.0, 0.35P CASE 517DP





1

SC-88 CASE 419B-02



D5, Z18 = Specific Device Code

KK = 2-Digit Lot Run Traceability Code
XY = 2-Digit Date Code Format
Z = Assembly Plant Code

M = Date Code ■ Pb-Free Package

(Note: Microdot may be in either location)

#### **ORDERING INFORMATION**

See detailed ordering, marking and shipping information in the package dimensions section on page 6 of this data sheet.

## **Pin Configurations**

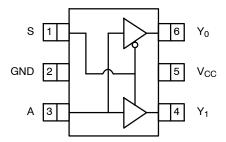


Figure 1. SC-88 (Top View)

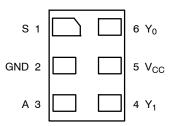
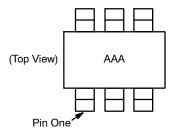


Figure 2. MicroPak (Top Through View)



#### NOTES:

- 1. AAA represents product code top mark (see Ordering Information).
- Orientation of top mark determines pin one location.
   Reading the top mark left to right, pin one is the lower left pin.

Figure 3. Pin 1 Orientation

#### **PIN DEFINITIONS**

Pin # SC-88	Pin # MicroPak	Name	Description
1	1	S	Data Input
2	2	GND	Ground
3	3	Α	Demultiplexer Data
4	4	Y <sub>1</sub>	Output
5	5	$V_{CC}$	Supply Voltage
6	6	Y <sub>0</sub>	Output

#### **FUNCTION TABLE**

Inp	uts	Output		
S	Α	Y <sub>0</sub>	Υ <sub>1</sub>	
L	L	L	Z	
L	Н	Н	Z	
Н	L	Z	L	
Н	Н	Z	Н	

H = HIGH Logic Level L = LOW Logic Level X = 3-STATE

#### **ABSOLUTE MAXIMUM RATINGS**

Symbol	Parameter	Min	Max	Unit	
V <sub>CC</sub>	Supply Voltage	-0.5	6.5	V	
V <sub>IN</sub>	DC Input Voltage		-0.5	6.5	V
V <sub>OUT</sub>	DC Output Voltage		-0.5	6.5	V
I <sub>IK</sub>	DC Input Diode Current	V <sub>IN</sub> < 0 V	=	-50	mA
I <sub>OK</sub>	DC Output Diode Current	V <sub>OUT</sub> < 0 V	=	-50	mA
I <sub>OUT</sub>	DC Output Current	=	±50	mA	
I <sub>CC</sub> or I <sub>GND</sub>	DC V <sub>CC</sub> or Ground Current	=	±100	mA	
T <sub>STG</sub>	Storage Temperature Range	-65	+150	°C	
TJ	Junction Temperature Under Bias	=	+150	°C	
TL	Junction Lead Temperature (Soldering	g, 10 Seconds)	=	+260	°C
P <sub>D</sub>	Power Dissipation at +85°C	SC-88	=	332	mW
		MicroPak-6	-	812	
		MicroPak2™-6	_	812	1
ESD	Human Body Model, JEDEC: JESD22-A114		-	2000	V
	Charge Device Model, JEDEC: JESD	22-C101	-	1000	1

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

#### **RECOMMENDED OPERATING CONDITIONS**

Symbol	Parameter	Conditions	Min	Max	Unit
V <sub>CC</sub>	Supply Voltage Operating		1.65	5.5	V
	Supply Voltage Data Retention		1.5	5.5	
V <sub>IN</sub>	Input Voltage		0	5.5	V
V <sub>OUT</sub>	Output Voltage		0	V <sub>CC</sub>	V
t <sub>r</sub> , t <sub>f</sub>	Input Rise and Fall Times	$V_{CC}$ at 1.8 V $\pm$ 0.15 V, 2.5 V $\pm$ 0.2 V	0	20	ns/V
		V <sub>CC</sub> at 3.3 V ±0.3 V	0	10	
		V <sub>CC</sub> at 5.0 V ±0.5 V	0	5	
T <sub>A</sub>	Operating Temperature		-40	+85	°C
$\theta_{\sf JA}$	Thermal Resistance	SC-88	-	377	°C/W
		MicroPak-6	-	154	
		MicroPak2-6	-	154	

Functional operation above the stresses listed in the Recommended Operating Ranges is not implied. Extended exposure to stresses beyond the Recommended Operating Ranges limits may affect device reliability.

#### DC ELECTRICAL CHARACTERISTICS

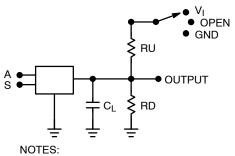
				T <sub>A</sub> = +25°C			T <sub>A</sub> = -40 to +85°C		
Symbol	Parameter	V <sub>CC</sub> (V)	Conditions	Min	Тур	Max	Min	Max	Unit
V <sub>IH</sub>	HIGH Level Input Voltage	1.65 to 1.95		0.65 V <sub>CC</sub>	_	-	0.75 V <sub>CC</sub>	-	V
		2.30 to 5.50		0.70 V <sub>CC</sub>	_	-	0.70 V <sub>CC</sub>	-	1
V <sub>IL</sub>	LOW Level Input Voltage	1.65 to 1.95		-	_	0.25 V <sub>CC</sub>	-	0.25 V <sub>CC</sub>	V
		2.30 to 5.50		_	_	0.30 V <sub>CC</sub>	-	0.30 V <sub>CC</sub>	1
V <sub>OH</sub>	OH HIGH Level Output Voltage	1.65	$V_{IN} = V_{IH}$ or $V_{IL}$	1.55	1.65	-	1.55	-	V
		2.30	I <sub>OH</sub> = -100 μA	2.20	2.30	-	2.20	_	1
		3.00	1	2.90	3.00	-	2.90	_	1
		4.50		4.40	4.50	-	4.40	_	1
		1.65	I <sub>OH</sub> = -4 mA	1.29	1.52	-	1.29	_	1
		2.30	I <sub>OH</sub> = -8 mA	1.90	2.15	-	1.90	_	
		3.00	I <sub>OH</sub> = -16 mA	2.40	2.80	-	2.40	-	
		3.00	I <sub>OH</sub> = -24 mA	2.30	3.68	-	2.30	-	
		4.50	I <sub>OH</sub> = -32 mA	3.80	4.20	-	3.80	-	
$V_{OL}$	LOW Level Output Voltage	1.65	$V_{IN} = V_{IH} \text{ or } V_{IL},$ $I_{OL} = 100  \mu\text{A}$	-	0.00	0.10	-	0.10	V
		2.30		_	0.00	0.10	-	0.10	
		3.00		_	0.00	0.10	-	0.10	
		4.50		_	0.00	0.10	-	0.10	
		1.65	I <sub>OL</sub> = 4 mA	-	0.08	0.24	-	0.24	
		2.30	I <sub>OL</sub> = 8 mA	-	0.10	0.30	-	0.30	
		3.00	I <sub>OL</sub> = 16 mA	-	0.15	0.40	-	0.40	
		3.00	I <sub>OL</sub> = 24 mA	-	0.22	0.55	-	0.55	
		4.50	I <sub>OL</sub> = 32 mA	-	0.22	0.55	-	0.55	
I <sub>IN</sub>	Input Leakage Current	1.65 to 5.5	V <sub>IN</sub> = 5.5 V, GND	-	-	±0.1	-	±1.0	μΑ
l <sub>OZ</sub>	3-STATE Output Leakage	1.65 to 5.5	$\begin{aligned} V_{IN} &= V_{IH} \text{ or } V_{IL}, \\ 0 &< V_{OUT} \leq 5.5 \text{ V} \end{aligned}$	-	_	±0.5	-	±5.0	μΑ
I <sub>OFF</sub>	Power Off Leakage Current	0	V <sub>IN</sub> or V <sub>OUT</sub> = 5.5 V	-	-	1	-	10	μΑ
Icc	Quiescent Supply Current	1.65 to 5.5	V <sub>IN</sub> = 5.5 V, GND	-	_	1	-	10	μА

#### **AC ELECTRICAL CHARACTERISTICS**

				T <sub>A</sub> = +25°C			T <sub>A</sub> = -40 to +85°C		
Symbol	Parameter	V <sub>CC</sub> (V)	Conditions	Min	Тур	Max	Min	Max	Unit
t <sub>PLH</sub> , t <sub>PHL</sub>	Propagation Delay A to (Y <sub>0</sub> or Y <sub>1)</sub>	1.80 ±0.15	_ ' '	_	6.3	10.1	_	10.5	ns
	(Figure 4, 6)	2.50 ±0.20	$R_D = 1 M\Omega,$ $V_1 = OPEN$	-	3.6	5.7	_	6.0	
		3.30 ±0.30	1	-	2.7	4.0	_	4.3	
		5.00 ±0.50	1	-	2.0	3.1	_	3.3	
		3.30 ±0.30		-	3.4	4.9	-	5.4	ns
		5.00 ±0.50	$R_D = 500 \Omega$ , $V_1 = OPEN$	-	2.5	3.9	-	4.2	
$t_{PZL}$ , $t_{PHZ}$	PZL, t <sub>PHZ</sub> Output Enable Time (Figure 4, 6)	1.80 ±0.15		-	6.9	12.0	_	12.5	ns
		2.50 ±0.20	$R_D$ , $R_U$ = 500 Ω, $V_1$ = GND for $t_{PZH}$ $V_1$ = $V_{IN}$ for $t_{PZL}$ $V_{IN}$ = 2 x $V_{CC}$	-	4.2	6.8	_	7.3	
		3.30 ±0.30		-	3.2	5.0	-	5.5	]
		5.00 ±0.50		-	2.5	4.0	-	4.3	
	Output Disable Time	1.80 ±0.15		-	6.0	10.0	_	10.5	ns
	(Figure 4, 6)	2.50 ±0.20	I V   - OI ID IOI IPEZ	-	4.0	6.8	_	7.1	
		3.30 ±0.30	$V_1 = V_{IN}$ for $t_{PLZ}$ $V_{IN} = 2 \times V_{CC}$	-	2.9	4.9	_	5.3	
		5.00 ±0.50		-	1.8	3.5	_	3.7	
C <sub>IN</sub>	Input Capacitance	0		-	2.5	-	-	-	pF
C <sub>OUT</sub>	Output Capacitance	0		-	4.0	-	-	-	pF
C <sub>PD</sub>	Power Dissipation Capacitance	3.30		-	16.0	-	-	_	pF
	(Note 4) (Figure 5)	5.00	1	-	19.5	-	-	-	

<sup>4.</sup> C<sub>PD</sub> is defined as the value of the internal equivalent capacitance which is derived from dynamic operating current consumption (I<sub>CCD</sub>) at no output loading and operating at 50% duty cycle. C<sub>PD</sub> is related to I<sub>CCD</sub> dynamic operating current by the expression: I<sub>CCD</sub> = (C<sub>PD</sub>) (V<sub>CC</sub>) (f<sub>IN</sub>) + (I<sub>CC</sub>static).

#### **AC Loading and Waveforms**



- 5.  $C_L$  includes load and stray capacitance. 6. Input PRR = 1.0 MHz,  $t_W$  = 500 ns.

Figure 4. AC Test Circuit

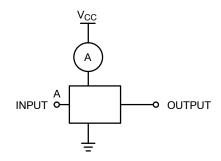
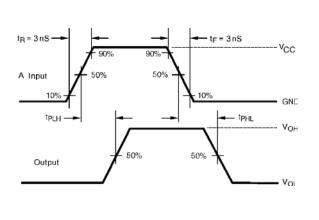


Figure 5. I<sub>CCD</sub> Test Circuit



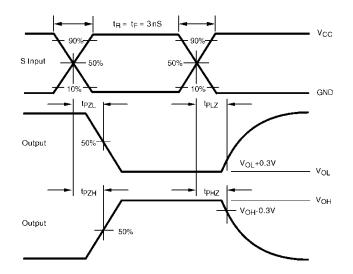


Figure 6. AC Waveforms

#### **ORDERING INFORMATION**

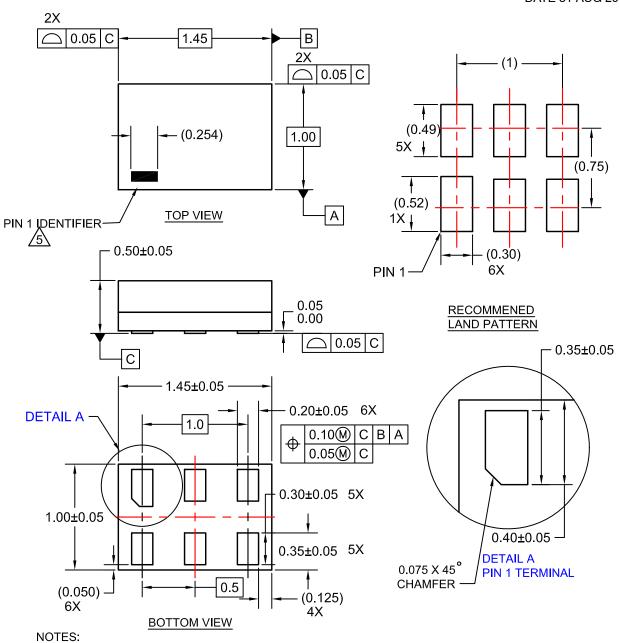
Device	Top Mark	Packages	Shipping <sup>†</sup>
NC7SZ18P6X	Z18	SC-88	3000 / Tape & Reel
NC7SZ18L6X	D5	SIP6, MicroPak	5000 / Tape & Reel
NC7SZ18FHX	D5	UDFN6, MicroPak2	5000 / Tape & Reel

<sup>†</sup>For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

#### **PACKAGE DIMENSIONS**

SIP6 1.45X1.0 CASE 127EB ISSUE O

**DATE 31 AUG 2016** 

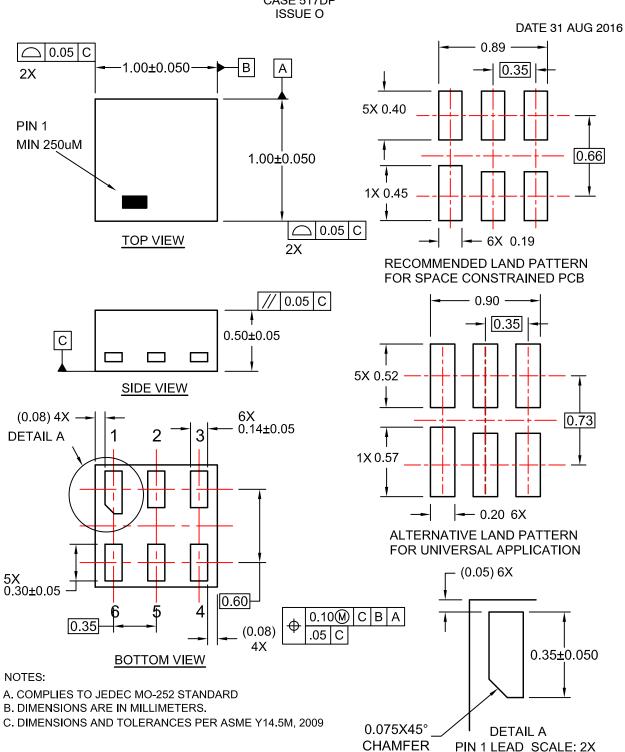


- 1. CONFORMS TO JEDEC STANDARD MO-252 VARIATION UAAD
- 2. DIMENSIONS ARE IN MILLIMETERS
- 3. DRAWING CONFORMS TO ASME Y14.5M-2009
- 4.PIN ONE IDENTIFIER IS 2X LENGTH OF ANY

OTHER LINE IN THE MARK CODE LAYOUT.

#### **PACKAGE DIMENSIONS**

# UDFN6 1.0X1.0, 0.35P CASE 517DP

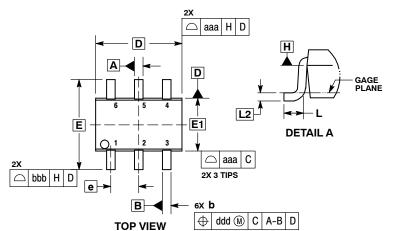


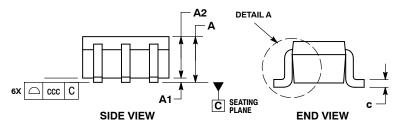
PIN 1 LEAD SCALE: 2X

#### PACKAGE DIMENSIONS

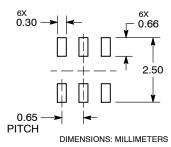
## SC-88/SC70-6/SOT-363

CASE 419B-02 **ISSUE Y** 





#### **RECOMMENDED SOLDERING FOOTPRINT\***



\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

- ITES:
  DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
  CONTROLLING DIMENSION: MILLIMETERS.
  DIMENSIONS D AND E1 DO NOT INCLUDE MOLD FLASH, PROTRUJSIONS, OR GATE BURRS. MOLD FLASH, PROTRUJSIONS, OR GATE BURRS SHALL NOT EXCEED 0.20 PER END.
  DIMENSIONS D AND E1 AT THE OUTERMOST EXTREMES OF THE PLASTIC BODY AND DATUM H.
  DATUMS A AND B ARE DETERMINED AT DATUM H.
  DIMENSIONS A AND CAPPLY TO THE FLAT SECTION OF THE

- DIMENSIONS b AND c APPLY TO THE FLAT SECTION OF THE LEAD BETWEEN 0.08 AND 0.15 FROM THE TIP.
- DIMENSION 6 DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 TOTAL IN EXCESS OF DIMENSION 6 AT MAXIMUM MATERIAL CONDITION. THE DAMBAR CANNOT BE LOCATED ON THE LOWER

	MIL	LIMETE	ERS	INCHES			
DIM	MIN	NOM	MAX	MIN NOM		MAX	
Α			1.10			0.043	
A1	0.00		0.10	0.000		0.004	
A2	0.70	0.90	1.00	0.027	0.035	0.039	
b	0.15	0.20	0.25	0.006	0.008	0.010	
С	0.08	0.15	0.22	0.003	0.006	0.009	
D	1.80	2.00	2.20	0.070	0.078	0.086	
E	2.00	2.10	2.20	0.078	0.082	0.086	
E1	1.15	1.25	1.35	0.045	0.049	0.053	
е		0.65 BS	С	0.026 BSC			
L	0.26	0.36	0.46	0.010	0.014	0.018	
L2		0.15 BSC			0.006 BSC		
aaa	0.15			0.006			
bbb	0.30			0.012			
ccc		0.10		0.004			
ddd		0.10			0.004		

#### **GENERIC MARKING DIAGRAM\***



XXX = Specific Device Code

= Date Code\*

= Pb-Free Package

(Note: Microdot may be in either location)

- \*Date Code orientation and/or position may vary depending upon manufacturing location.
- \*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "■", may or may not be present. Some products may not follow the Generic Marking.

#### **STYLES ON PAGE 2**

#### SC-88/SC70-6/SOT-363 CASE 419B-02 **ISSUE Y**

STYLE 1: PIN 1. EMITTER 2 2. BASE 2 3. COLLECTOR 1 4. EMITTER 1 5. BASE 1 6. COLLECTOR 2	STYLE 2: CANCELLED	STYLE 3: CANCELLED	STYLE 4: PIN 1. CATHODE 2. CATHODE 3. COLLECTOR 4. EMITTER 5. BASE 6. ANODE	STYLE 5: PIN 1. ANODE 2. ANODE 3. COLLECTOR 4. EMITTER 5. BASE 6. CATHODE	STYLE 6: PIN 1. ANODE 2 2. N/C 3. CATHODE 1 4. ANODE 1 5. N/C 6. CATHODE 2
STYLE 7: PIN 1. SOURCE 2 2. DRAIN 2 3. GATE 1 4. SOURCE 1 5. DRAIN 1 6. GATE 2	STYLE 8: CANCELLED	STYLE 9: PIN 1. EMITTER 2 2. EMITTER 1 3. COLLECTOR 1 4. BASE 1 5. BASE 2 6. COLLECTOR 2	STYLE 10: PIN 1. SOURCE 2 2. SOURCE 1 3. GATE 1 4. DRAIN 1 5. DRAIN 2 6. GATE 2	STYLE 11: PIN 1. CATHODE 2 2. CATHODE 2 3. ANODE 1 4. CATHODE 1 5. CATHODE 1 6. ANODE 2	STYLE 12: PIN 1. ANODE 2 2. ANODE 2 3. CATHODE 1 4. ANODE 1 5. ANODE 1 6. CATHODE 2
STYLE 13: PIN 1. ANODE 2. N/C 3. COLLECTOR 4. EMITTER 5. BASE 6. CATHODE	STYLE 14: PIN 1. VREF 2. GND 3. GND 4. IOUT 5. VEN 6. VCC	STYLE 15: PIN 1. ANODE 1 2. ANODE 2 3. ANODE 3 4. CATHODE 3 5. CATHODE 2 6. CATHODE 1	STYLE 16: PIN 1. BASE 1 2. EMITTER 2 3. COLLECTOR 2 4. BASE 2 5. EMITTER 1 6. COLLECTOR 1	STYLE 17: PIN 1. BASE 1 2. EMITTER 1 3. COLLECTOR 2 4. BASE 2 5. EMITTER 2 6. COLLECTOR 1	STYLE 18: PIN 1. VIN1 2. VCC 3. VOUT2 4. VIN2 5. GND 6. VOUT1
STYLE 19: PIN 1. I OUT 2. GND 3. GND 4. V CC 5. V EN 6. V REF	STYLE 20: PIN 1. COLLECTOR 2. COLLECTOR 3. BASE 4. EMITTER 5. COLLECTOR 6. COLLECTOR	STYLE 21: PIN 1. ANODE 1 2. N/C 3. ANODE 2 4. CATHODE 2 5. N/C 6. CATHODE 1	STYLE 22: PIN 1. D1 (i) 2. GND 3. D2 (i) 4. D2 (c) 5. VBUS 6. D1 (c)	STYLE 23: PIN 1. Vn 2. CH1 3. Vp 4. N/C 5. CH2 6. N/C	STYLE 24: PIN 1. CATHODE 2. ANODE 3. CATHODE 4. CATHODE 5. CATHODE 6. CATHODE
STYLE 25: PIN 1. BASE 1 2. CATHODE 3. COLLECTOR 2 4. BASE 2 5. EMITTER 6. COLLECTOR 1	STYLE 26: PIN 1. SOURCE 1 2. GATE 1 3. DRAIN 2 4. SOURCE 2 5. GATE 2 6. DRAIN 1	STYLE 27: PIN 1. BASE 2 2. BASE 1 3. COLLECTOR 1 4. EMITTER 1 5. EMITTER 2 6. COLLECTOR 2	STYLE 28: PIN 1. DRAIN 2. DRAIN 3. GATE 4. SOURCE 5. DRAIN 6. DRAIN	STYLE 29: PIN 1. ANODE 2. ANODE 3. COLLECTOR 4. EMITER 5. BASE/ANODE 6. CATHODE	STYLE 30: PIN 1. SOURCE 1 2. DRAIN 2 3. DRAIN 2 4. SOURCE 2 5. GATE 1 6. DRAIN 1

Note: Please refer to datasheet for style callout. If style type is not called out in the datasheet refer to the device datasheet pinout or pin assignment.

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